

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	WENG-JIN WU	08/13/2018
RECEIVING PARTY DATA		
Name:	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC	
Street Address:	5005 E. MCDOWELL ROAD	
Internal Address:	MAILDROP A700	
City:	PHOENIX	
State/Country:	ARIZONA	
Postal Code:	85008	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	16101567
CORRESPONDENCE DATA		
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
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Correspondent Name:	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC	
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ATTORNEY DOCKET NUMBER:	ONS02897US	
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SIGNATURE:	/Sharron Castillo/	
DATE SIGNED:	08/13/2018	
Total Attachments: 2		
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source=ONS02897US_20180813_Assignment#page2.tif		

ASSIGNMENT & AGREEMENT

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I,

Name _____ of (City and State OR Country) _____

WENG-JIN WU

HSINCHU CITY TAIWAN

agree to sell, assign, and transfer, and do hereby sell, assign, and transfer to Semiconductor Components Industries, LLC, a limited liability company of the State of Delaware, having its principal office in Phoenix, State of Arizona, United States of America, and its successors, assigns, and legal representatives ("SCI"), the entire right, title, and interest in and to the inventions and discoveries as described, illustrated, and/or claimed in

Title: PACKAGING STRUCTURE FOR A SENSOR HAVING A SEALING LAYER

Attorney Docket No.: ONS02897US

Serial No.: 16/101567

Filing Date: August 13, 2018

together with the entire right, title, and interest in and to the above listed application(s), and in and to any and all provisional, non-provisional, divisional, continuation, continuation-in-part, international, foreign, and any and all other applications related thereto, and also including any and all grants, issuances, letters patent, reissues, reexaminations, renewals, priority rights, and priority claims related to any of the foregoing, and any and all rights to collect past damages for infringement of any of the foregoing (the "Patent Rights").

I further authorize SCI to apply for and hold and maintain the Patent Rights throughout the world directly in its own name or any other name which SCI deems appropriate in its sole discretion, and to claim the priority of the filing date of the above listed application(s).

I agree that, when requested, I will, without charge to SCI, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing, maintaining, and enforcing the Patent Rights in any and all countries and for vesting title thereto in SCI or its nominees.

I represent and warrant that I have full right to convey the entire right, title and interest herein sold, assigned, and transferred, and that the Patent Rights hereby conveyed are free from all prior assignment, grant, mortgage, license, or other encumbrance to anyone other than SCI. I covenant and further warrant that I will not convey hereafter any part of the Patent Rights to anyone other than SCI or do any act whatsoever conflicting with this ASSIGNMENT & AGREEMENT.

I hereby authorize SCI or anyone it may properly designate to insert in this ASSIGNMENT & AGREEMENT the filing date and serial number of the above listed application(s) when ascertained. More than one counterpart of this ASSIGNMENT & AGREEMENT may be executed, each of which will be deemed an original.

By (Inventor signature): Weng-Jin Wu
Weng-Jin Wu

Witnessed by (Witness signature): Wei-Chun, Chao

Printed name of Witness: Wei-Chun, Chao

Signed and Witnessed on (date): 13rd Aug. 2018